| Product name: | Product code: |
| --- | --- |
| PCB Electroless Copper Deposition Bath | CMI-NP-1827 |




## Description

PCB Electroless Copper Deposition Bath is a heated bath for electroless copper deposition on prepared hole walls.

## Technical specification

- Anodes
- Racks
- Chemical kit

The PCB Electroless Copper Deposition Bath is a heated bath for electroless copper deposition on prepared hole walls. It is designed for through-hole plating and chemical metallization of double sided and multilayer PCBs in a lab.

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**Features**

- Digital temperature control unit
- Fume extraction connection
- Complete small-scale hole plating process
- Heated and agitated tanks for uniform plating

**Technical Specifications**

| | |
|---|---|
| Bath volume | 20 L |
| Temp control | +/- 1 deg C |
| Agitation | Air bubbling |
| Supply | 230 V AC, 50 Hz, single phase |
| Tank material | Polypropylene |
| Heater | PTFE or titanium, with controller |

**Standard Accessories**